

WHAT IS CLAIMED IS:

1. A cleaning apparatus comprising:
 - multiple kinds of cleaning modules each configured to perform a cleaning processing of a substrate;
 - an accommodating section configured to accommodate the multiple kinds of cleaning modules therein;
 - a fluid supply section configured to supply a fluid to a cleaning module accommodated in the accommodating section through a pipe; and
 - a controller configured to control a discharge pressure of a fluid supplied in each cleaning module based on the pressure loss of the pipe in the cleaning module when the pipe and the cleaning module are connected through a pipe connection portion, wherein each of the multiple kinds of cleaning modules includes a pipe connection portion having a common connection position to be connected with the pipe.
2. The cleaning apparatus of claim 1, wherein the fluid supply section includes a pure water pipe configured to supply pure water as the fluid, a chemical liquid pipe configured to supply a chemical liquid as the fluid, and an air pipe configured to supply air for driving the cleaning modules as the fluid, and
 - the pipe connection portion is connected to at least one of the pure water pipe, the chemical liquid pipe, and the air pipe.
3. The cleaning apparatus of claim 1, wherein at least one of the multiple kinds of cleaning modules includes:
 - a roll cleaning module including a first rotation mechanism configured to rotate

the substrate, a first top surface fluid supply nozzle configured to supply the fluid to a top surface of the substrate, a first bottom surface fluid supply nozzle configured to supply the fluid to a bottom surface of the substrate, and a roll cleaning member configured to rotate while bringing a peripheral surface thereof into contact with the substrate; and

a pencil cleaning module including a second rotation mechanism configured to rotate the substrate, a second top surface fluid supply nozzle configured to supply the fluid to the top surface of the substrate, a second bottom surface fluid supply nozzle configured to pass through a rotating shaft of the second rotation mechanism and supply the fluid to the bottom surface of the substrate, and a pencil cleaning member configured to rotate by bringing an end surface thereof into contact with the substrate, and

the pencil cleaning module further includes:

a pipe extension portion configured to communicate with the second bottom surface fluid supply nozzle, led to an outside of a module case from the rotating shaft of the second rotation mechanism, and installed to extend to a connection position at which the first bottom surface fluid supply nozzle is connected to the pipe; and

a pipe cover attached to the module case to cover the pipe extension portion.

4. The cleaning apparatus of claim 1, wherein at least one of the multiple kinds of cleaning modules comprises a cleaning module one of selected from a two-fluid cleaning module, a buff cleaning module, and an edge cleaning module.

5. The cleaning apparatus of claim 1, wherein each of the multiple kinds of cleaning modules includes a module case having a common size.

6. The cleaning apparatus of claim 1, further comprising:
a second accommodating section configured to accommodate the fluid supply section in a manner in which the fluid supply section is capable of being drawn out,
wherein the fluid supply section includes the pipe and a second pipe that is different from the pipe, and
all pipes including the pipe and the second pipe are connected to a front side or an inner side of the fluid supply section in a drawing-out direction,
wherein the accommodating section accommodates the multiple kinds of cleaning modules to be superimposed one on another in a height direction.
7. The cleaning apparatus of claim 1, wherein at least one of the multiple kinds of cleaning modules includes:
a substrate holding unit configured to horizontally hold the bottom surface of the substrate;
a module side fluid supply unit configured to supply the fluid to the bottom surface of the substrate held by the substrate holding unit; and
a cleaning member configured to comes into contact with and clean the bottom surface of the substrate while the substrate is held by the substrate holding unit.
8. A substrate processing apparatus comprising:
a substrate transfer section configured to transfer a substrate;
a polishing section configured to polish the substrate; and
a cleaning section configured to clean the substrate,
wherein the cleaning section includes the cleaning apparatus of claim 1.
9. A substrate processing apparatus comprising:

a housing;

a plurality of liquid processing modules provided in the housing and configured to perform a liquid processing on a substrate;

a fluid supply configured to supply a fluid to the plurality of liquid processing modules accommodated in the housing via a pipe; and

a frame configured to accommodate the plurality of liquid processing modules in such a way that each of the plurality of liquid processing modules is drawn out;

wherein the plurality of liquid processing modules stacked and installed in a vertical direction,

each of the plurality of liquid processing modules includes a pipe connection portion connected to the fluid supply via the pipe, and

each of the plurality of pipes connecting the fluid supply and the pipe connection portion of the liquid processing module has a length capable of drawing out the plurality of liquid processing modules while being connected to the fluid supply.